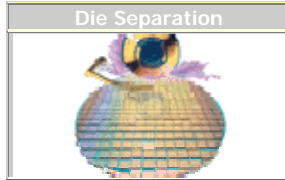




Dynatex Wafer Dicing System Advantages



The stream of KerfAid treated deionized (DI) water delivered to the dicing operation reduces thermal stress, die edge damage and internal cracking, assuring long-term integrity of the devices being processed. Since KerfAid is a coolant and lubricant, both the dicing blade and the device benefit. As a coolant, KerfAid reduces heat caused by friction. As a lubricant, KerfAid lowers friction and surface tension, which increases swarf dispersion.

- **Reduces Surface Tension** by 25-40 dynes/cm². KerfAid allows more water into the kerf, dissipating heat generated by friction.
- **Bonds Water Molecules** into the kerf and to the dicing blade, allowing better swarf dispersion and lubrication.
- **Prevents Swarf Accumulation** on the dicing blade and in streets, minimizing chipping and internal cracking.
- **Extends Blade Life** by up to 30%. The lubricated blade runs cooler, reducing metal fatigue and blade wear.
- **Improves Die Yield and Reliability** from the reduced amount of chipping, cracking and consequent edge damage.
- **Eliminates Scrubbing** after dicing.